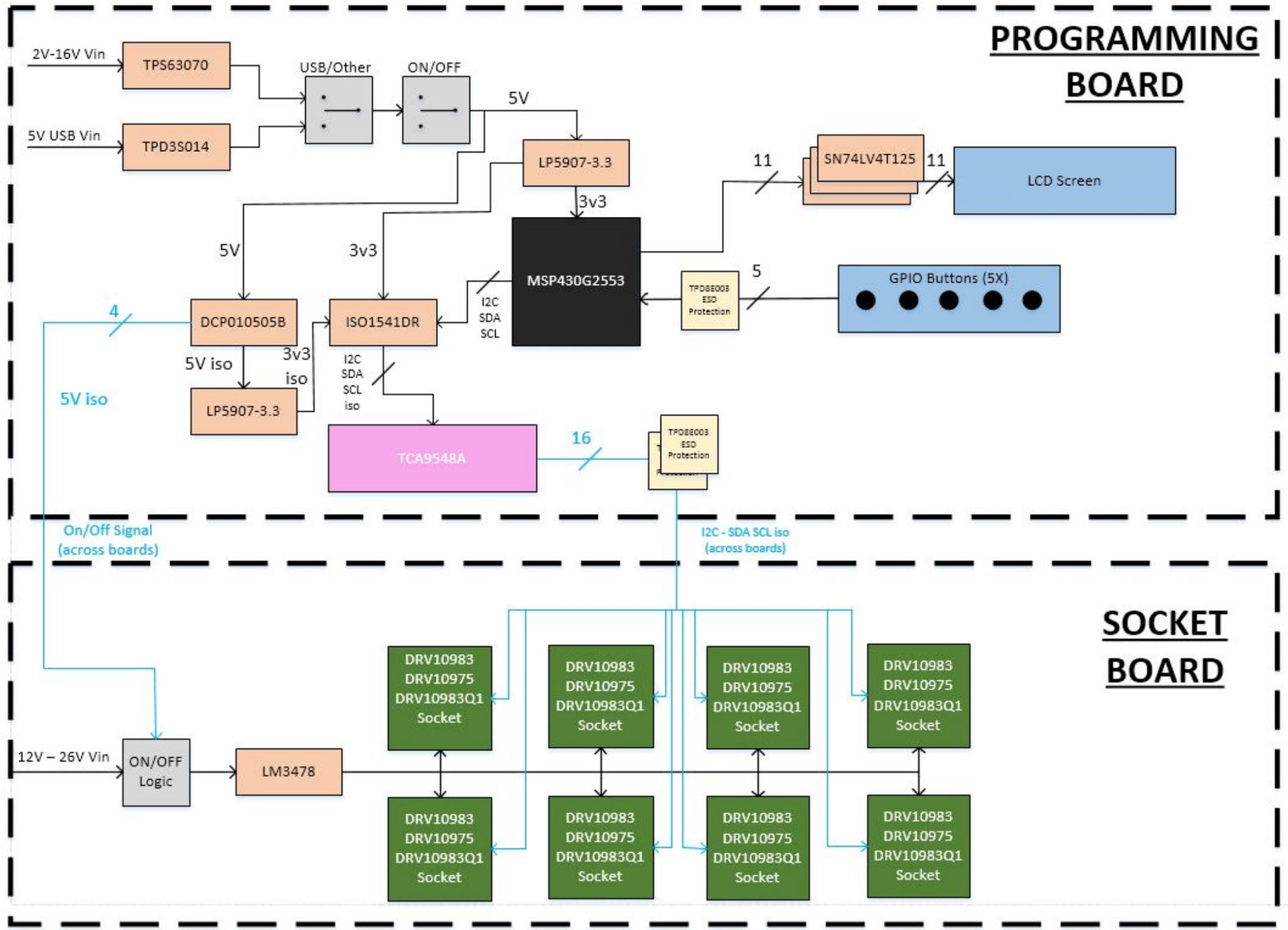
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



Orderable: ChangeMe!	Designed for:	Mod. Date: 2/23/2017
TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: TIDA01373_SB_CoverSheet.SchDoc	Size: B
Engineer: Michael Schneider	Contact: http://www.ti.com/support	

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Test Points

SCL0-TG
SCL0-TG

SCL1-TG
SCL1-TG

SCL2-TG
SCL2-TG

SCL3-TG
SCL3-TG

SCL4-TG
SCL4-TG

SCL5-TG
SCL5-TG

SCL6-TG
SCL6-TG

SCL7-TG
SCL7-TG

SDA0-TG
SDA0-TG

SDA1-TG
SDA1-TG

SDA2-TG
SDA2-TG

SDA3-TG
SDA3-TG

SDA4-TG
SDA4-TG

SDA5-TG
SDA5-TG

SDA6-TG
SDA6-TG

SDA7-TG
SDA7-TG

24v
24v

ON/OFF
ON/OFF

VSource
VSource

Orderable: ChangeMe!	Designed for:	Mod. Date: 2/1/2017
TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA01373_SB_TestPoints.SchDoc	Size: B
Engineer: Michael Schneider	Contact: http://www.ti.com/support	

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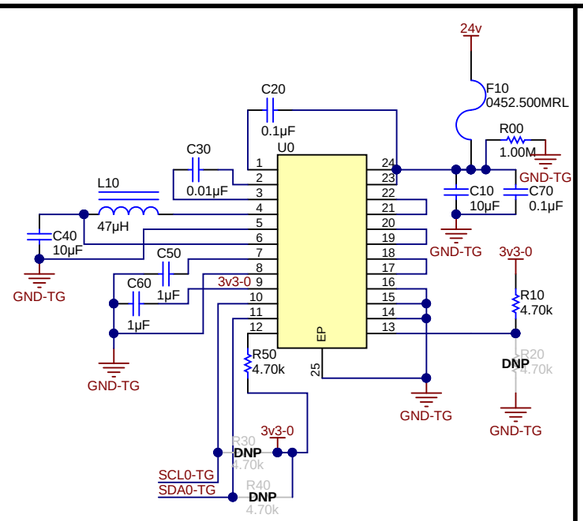
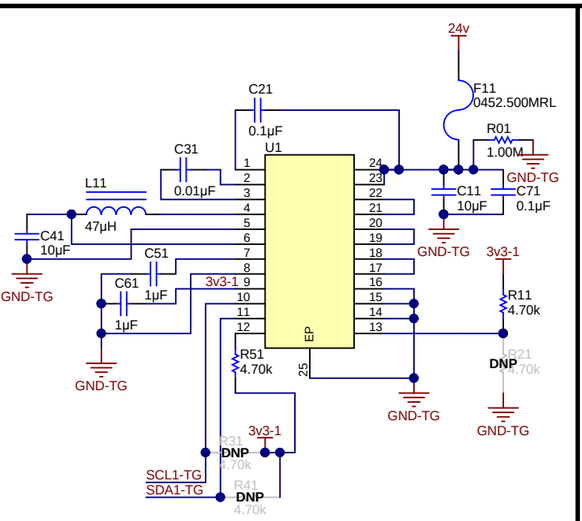
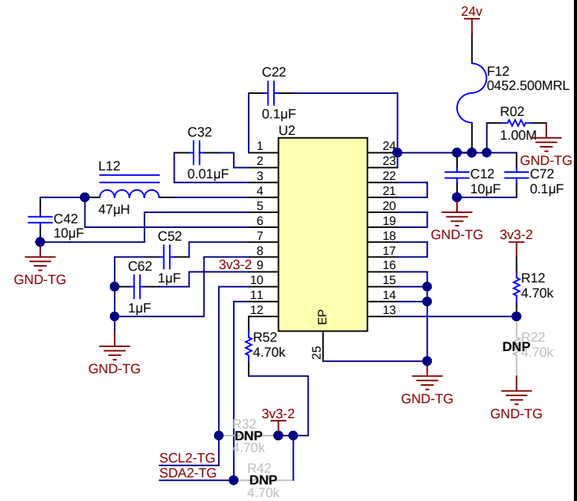
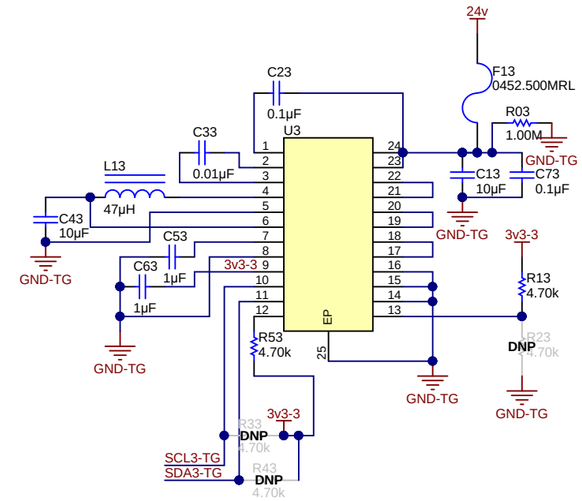
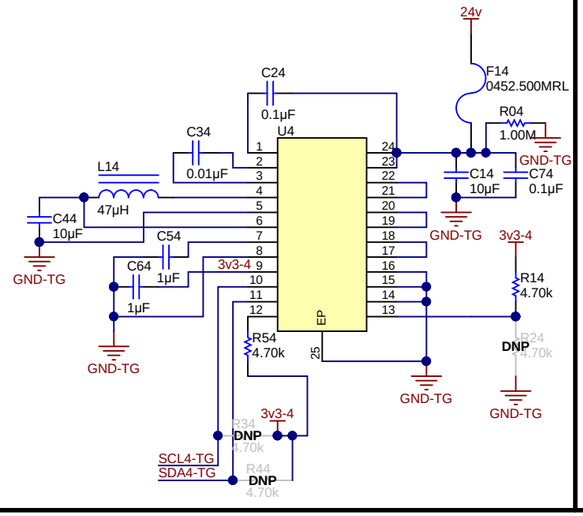
Sockets

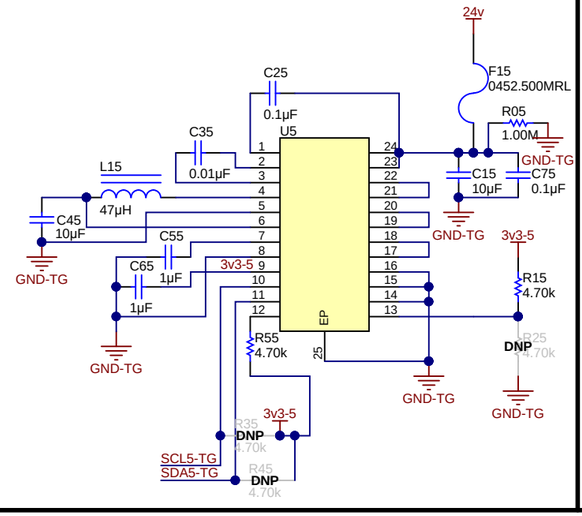


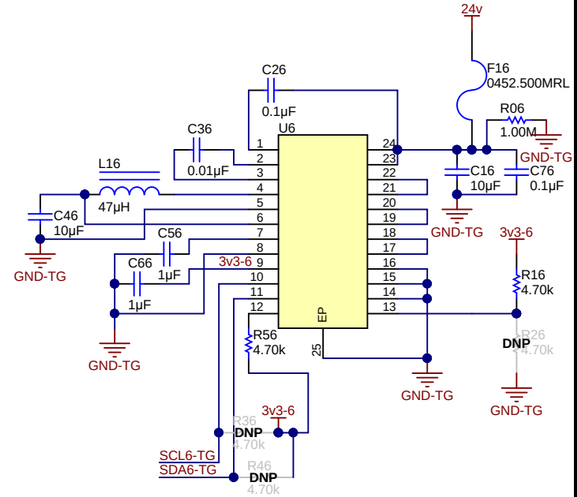


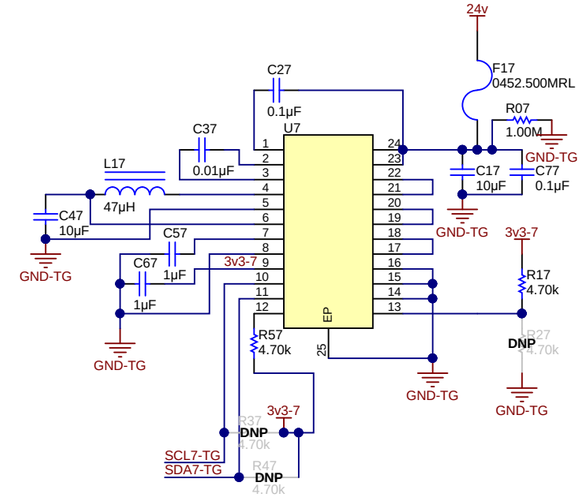












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TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA01373_SB_Sockets.SchDoc	Size: B
Engineer: Michael Schneider	Contact: http://www.ti.com/support	

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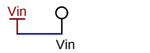
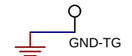
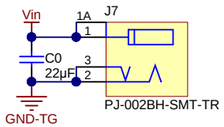
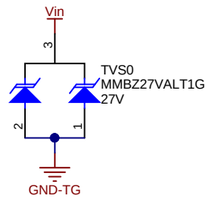
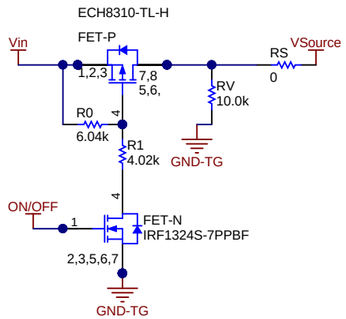
DC Power Layout

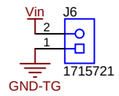


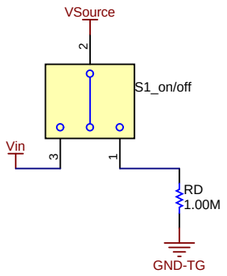


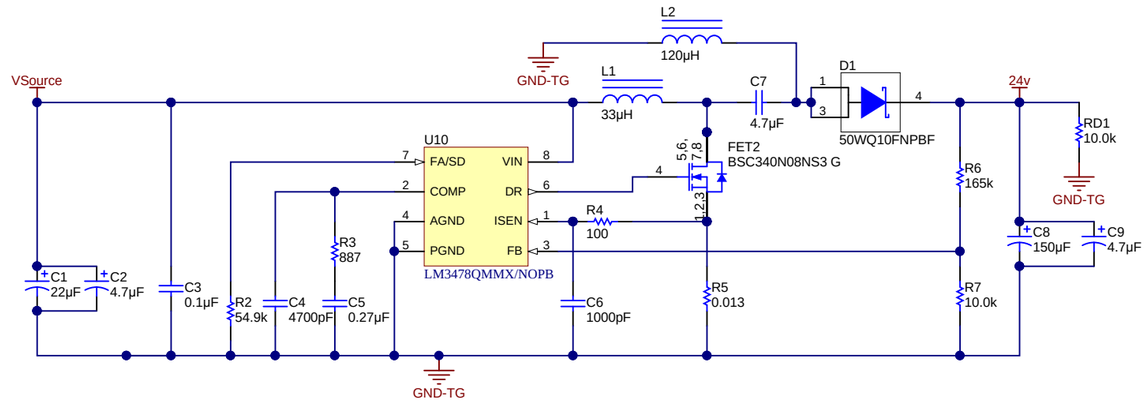












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TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA01373_SB_Power_Stage.SchDoc	Size: B
Engineer: Michael Schneider	Contact: http://www.ti.com/support	

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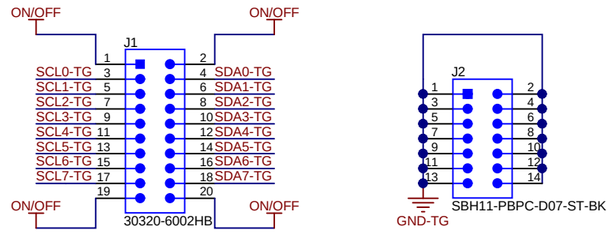
I2C

I2C Download Port



Orderable: ChangeMe!	Designed for:	Mod. Date: 2/2/2017
TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA01373_SB_I2C.SchDoc	Size: B
Engineer: Michael Schneider	Contact: http://www.ti.com/support	

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H1 1 NY PMS 440 0025 PH

H2 1 NY PMS 440 0025 PH

H3 1 NY PMS 440 0025 PH

H4 1 NY PMS 440 0025 PH

H5 1902C

H6 1902C

H7 1902C

H8 1902C

DNP FID1

DNP FID2

DNP FID3

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

Orderable: ChangeMe!	Designed for:	Mod. Date: 2/1/2017
TID #: TIDA-01373	Project Title: TIDA-01373 - Socket Board	
Number: TIDA-01373 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA01373_SB_Hardware.SchDoc	Size: B
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